

Preliminary Product Information Sheet

EPO-TEK® Additive AP100

Note: These are typical properties to be used as a guide only, not a specification. Data below is not guaranteed.

Different batches, conditions and applications yield differing results.

Date: September 2017 Recommended Cure: N/A

Rev: II

No. of Components: Single
Mix Ratio by Weight: N/A

Specific Gravity: 1.08
Pot Life: N/A

Shelf Life- Bulk: One year at room temperature

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

<u>Product Description:</u> AP-100 is an all-purpose adhesion promoter. It can be used on glasses, metals, ceramics and most plastics found in electronic assembly and optical packaging applications.

MATERIAL CHARACTERISTICS*:

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PHYSICAL PROPERTIES:	Cure condition: N/A
Color (before cure):	Clear
Consistency:	Pourable liquid
Viscosity (23°C) @ 100 rpm:	757 cPs
Thixotropic Index:	N/A
Glass Transition Temp:	N/A
Coefficient of Thermal Expansion (CT	E):
Below	Tg: N/A
Above	Tg: N/A
Shore D Hardness:	N/A
Lap Shear @ 23°C:	N/A
Die Shear @ 23°C:	N/A
Degradation Temp:	N/A
Weight Loss:	
@ 200	°C: N/A
@ 250	°C: N/A
@ 300	°C: N/A
Suggested Operating Temperature:	N/A
Storage Modulus:	N/A
Particle Size:	N/A

APPLICATIONS NOTES:

- 1. As primer onto surfaces before applying epoxy resin: Make a solution of ethanol/AP100 at concentration of 99/1 parts by weight (anhydrous ethanol suggested). Mix solution until it is homogenous, and then used as primer onto desired parts. Allow parts to air dry, or can use oven drying at 80°C/30 Minutes. The parts are now successfully primed and ready for the EPO-TEK® product to be used.
- 2. As additive into the epoxy resin: Simply mix 0-1.5% PBW into the already mixed epoxy resin. Remix until the AP100 is homogenously mixed throughout the EPO-TEK® product. Apply onto your parts for epoxy resin adhesive gluing.

The data above is INITIAL only - it may be changed at any time, for any reason without notice to anyone. It is provided only as a guide for evaluation/consideration.

^{*} These material characteristics are typical properties that are based on a limited number of samples/batches. All properties are based on the cure indicated above. Some properties may vary as manufactured quantities are scaled up to commercialized production levels.